

LAPIS Technology LSI Part No. Explanation

Structure of Product Name

4 Derived Code 6 Option Classification Symbol 2 Device Code 3 Character Symbol 5 Package Symbol

Assignment of Symbols

1 Device Function

The device functions are classified as follows.

MD: DRAM

1 Device Function

MR: P2ROM™, OTPROM

MS: Video Memory

ML: Logic

MK: Module, Chip Set

MT: Driver

2 Device Code

The device code expresses a function specific to a device using a combination of numbers and alphanumeric characters.

3 Character Symbol

The character symbol is added to indicate the modification of an existing product, to emphasize a specification that differs from the standard specification of an existing product, or to indicate a design standard.

4 Derived Code

The derived code indicates the speed ranking for DRAM products and is used as a derived code for logic products.

5 Package Symbol

The package symbol expresses the type and lead bending profile of a package in two digits.

6 Option Classification Symbol

The option classification symbol is used to distinguish between the option code and the package symbol.

7 Option Code

The option code indicates a symbol that identifies the specification of a product with an option.

Product Name of Conventional Product

The following shows the convention of item name assignment for conventional products.

1 Process Classification 2 Circuit Category 3 Package Profile

- 1 Process Classification
- A: Analog
- C: Bi-CMOS, multi-chip product
- L: Bipolar logic
- M: MOS

- 2 Circuit Category Indicates the circuit category.
 - 3 Package Profile

Indicates the package profile.

Please note that the contents are subject to change without notice.



^{*} The actual package profile is not shown here.